

### ESD73034D

# 4-Lines, Bi-directional, Ultra-low Capacitance Transient Voltage Suppressors

## **Descriptions**

The ESD73034D is an ultra-low capacitance TVS (Transient Voltage Suppressor) array designed to protect high speed data interfaces. It has been specifically designed to protect sensitive electronic components which are connected to data and transmission lines from over-stress caused by ESD (Electrostatic Discharge).

The ESD73034D incorporates four pairs of ultra-low capacitance steering diodes plus a TVS diode.

The ESD73034D may be used to provide ESD protection up to  $\pm 10 \text{kV}$  (contact discharge) according to IEC61000-4-2, and withstand peak pulse current up to 5.5A (8/20 $\mu$ s) according to IEC61000-4-5.

The ESD73034D is available in DFN2510-10L package. Standard products are Pb-free and Halogen-free.

### **Features**

- Stand-off voltage: ±3.3V Max.
- Transient protection for each line according to IEC61000-4-2 (ESD): ±10kV (contact discharge)

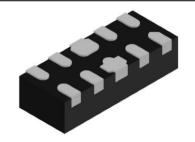
IEC61000-4-4 (EFT): 40A (5/50ns) IEC61000-4-5 (surge): 5.5A (8/20µs)

- Ultra-low capacitance: C<sub>J</sub> = 0.2pF typ.
- Low leakage current
- Low clamping voltage:  $V_{CL} = 8.7V$  typ. @  $I_{PP} = 16A$  (TLP)
- Solid-state silicon technology

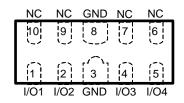
## **Applications**

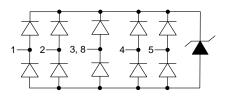
- USB 3.0 and USB 3.1
- HDMI 1.3, HDMI 1.4 and HDMI 2.0
- Portable Electronics and Notebooks

### http//:www.sh-willsemi.com



### DFN2510-10L (Bottom view)





Pin configuration (Top view)



TG = Device code
YW = Date code
Marking

### Order information

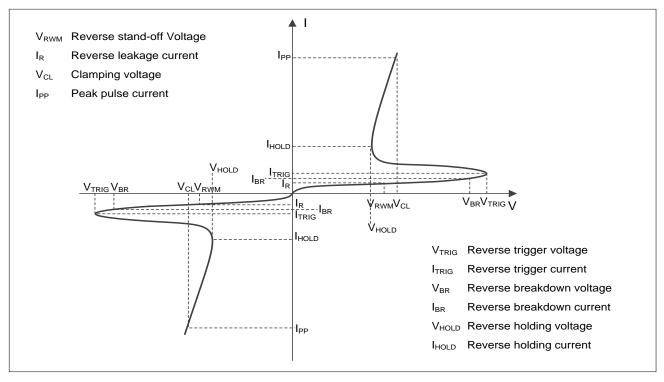
Device	Package	Shipping	
ESD73034D-10/TR	DFN2510-10L	3000/Tape&Reel	



## **Absolute maximum ratings**

Parameter	Symbol	Rating	Unit	
Peak pulse power ( $t_p = 8/20\mu s$ )	$P_{pk}$	33	W	
Peak pulse current (t <sub>p</sub> = 8/20µs)	I <sub>PP</sub>	5.5	А	
ESD according to IEC61000-4-2 air discharge	V	±15	kV	
ESD according to IEC61000-4-2 contact discharge	$V_{ESD}$	±10		
Junction temperature	TJ	125	°C	
Operating temperature	T <sub>OP</sub>	-40~85	°C	
Lead temperature	TL	260	°C	
Storage temperature	T <sub>STG</sub>	-55~150	°C	

## Electrical characteristics (T<sub>A</sub>=25 °C, unless otherwise noted)



**Definitions of electrical characteristics** 



## Electrical characteristics (T<sub>A</sub> = 25 °C, unless otherwise noted)

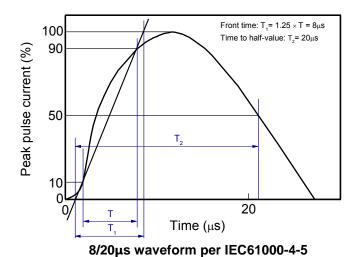
Parameter	Symbol	Condition Min.		Тур.	Max.	Unit
Reverse maximum working voltage	$V_{RWM}$				3.3	V
Reverse leakage current	I <sub>R</sub>	$V_{RWM} = 3.3V$			100	nA
Reverse breakdown voltage	$V_{BR}$	I <sub>T</sub> = 100μA	9		12	V
Clamping voltage 1)	V <sub>CL</sub>	$I_{PP} = 16A, t_p = 100ns$		8.7		V
Dynamic resistance 1)	R <sub>DYN</sub>			0.38		Ω
Clamping voltage 2)	V <sub>CL</sub>	V <sub>ESD</sub> = 8kV		10		V
Clamping voltage 3)	V <sub>CL</sub>	$I_{PP} = 1A, t_p = 8/20 \mu s$			3.5	V
		$I_{PP} = 5.5A, t_p = 8/20 \mu s$			6.0	V
Junction capacitance	CJ	V <sub>R</sub> = 1.5V, f = 1MHz 0.2		0.2	0.28	pF

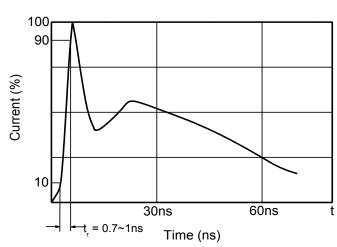
#### Notes

- 1) TLP parameter:  $Z_0 = 50 \ \Omega$ ,  $t_p = 100$ ns,  $t_r = 2$ ns, averaging window from 60ns to 80ns.  $R_{DYN}$  is calculated from 4A to 16A.
- 2) Contact discharge mode, according to IEC61000-4-2.
- 3) Non-repetitive current pulse, according to IEC61000-4-5.

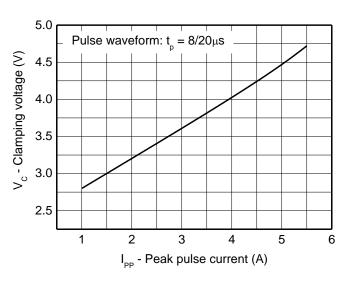


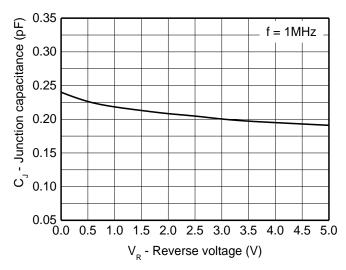
## Typical characteristics (T<sub>A</sub> = 25 °C, unless otherwise noted)





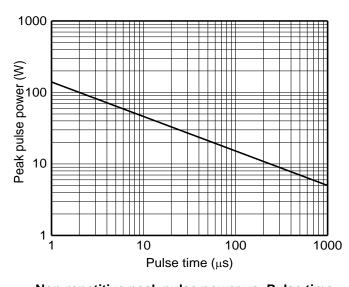
Contact discharge current waveform per IEC61000-4-2

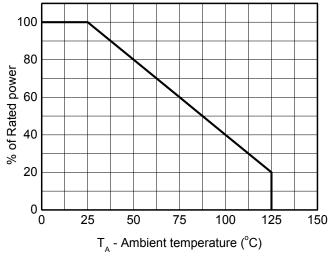




Clamping voltage vs. Peak pulse current

Capacitance vs. Reverse voltage



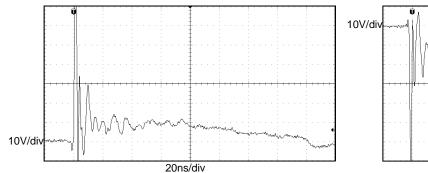


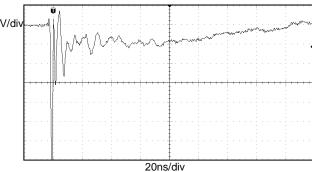
Non-repetitive peak pulse power vs. Pulse time

Power derating vs. Ambient temperature



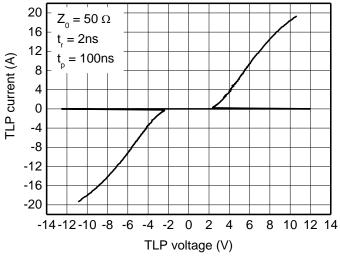
## Typical characteristics (T<sub>A</sub> = 25 °C, unless otherwise noted)





ESD clamping (+8kV contact discharge per IEC61000-4-2)

ESD clamping (-8kV contact discharge per IEC61000-4-2)

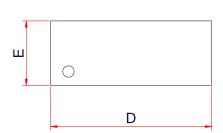


**TLP Measurement** 

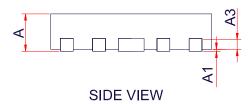


## Package outline dimensions

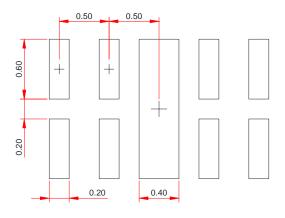
## **DFN2510-10L**

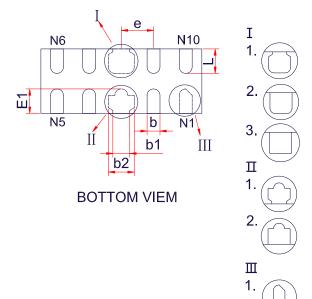


**TOP VIEW** 



## **Recommended Land Pattern (Unit: mm)**





Symbol	Dimensions in millimeter				
Symbol	Min. Typ.		Max.		
А	0.50	0.55	0.60		
A1	0.00	0.02	0.05		
А3	0.15 Ref.				
D	2.40	2.50	2.60		
E	0.90	1.00	1.10		
E1	0.50 Ref.				
b	0.15	0.15 0.20 0			
b1	0.13	0.18	0.23		
b2	0.35 0.40		0.45		
е	0.50 BSC				
L	0.28 0.39 0.50				

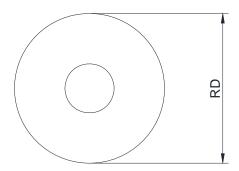
## Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

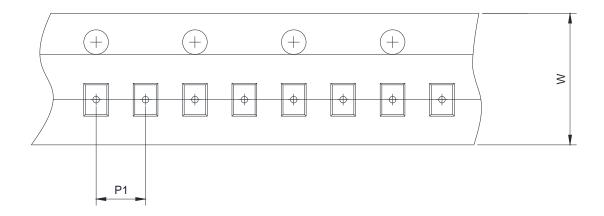


## TAPE AND REEL INFORMATION

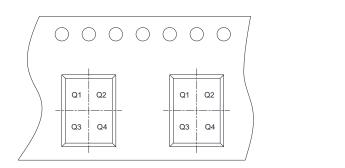
## **Reel Dimensions**



**Tape Dimensions** 



## **Quadrant Assignments For PIN1 Orientation In Tape**





RD	Reel Dimension	<b>▼</b> 7inch	☐ 13inch		
W	Overall width of the carrier tape	<b>▼</b> 8mm	☐ 12mm		
P1	Pitch between successive cavity centers	☐ 2mm	<b>✓</b> 4mm	☐ 8mm	
Pin1	Pin1 Quadrant	<b>☑</b> Q1	□ Q2	□ Q3	□ Q4